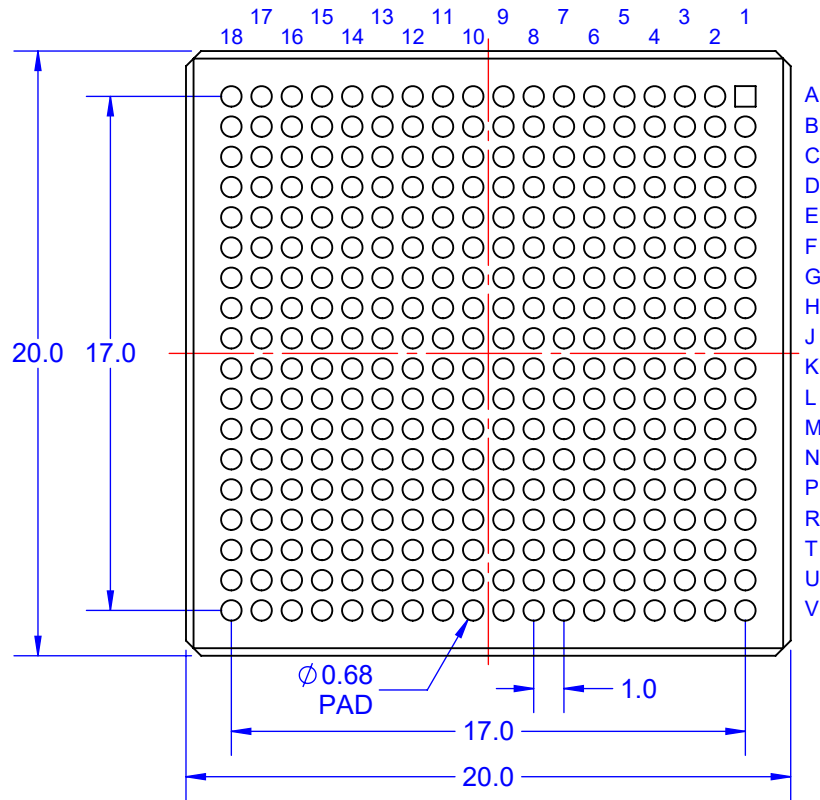
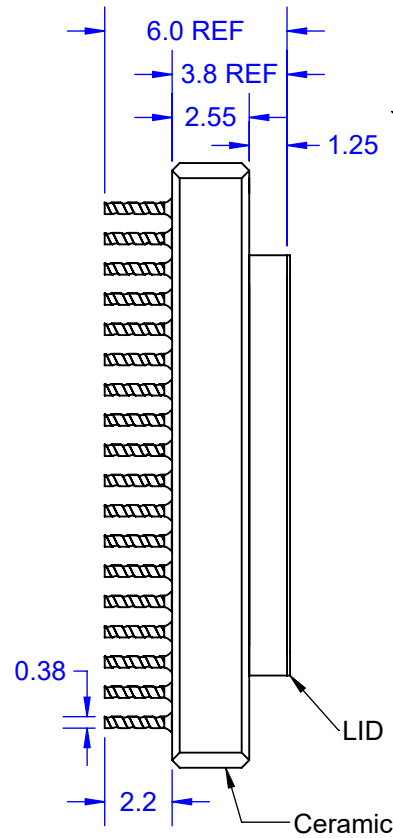


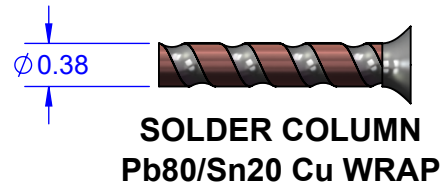
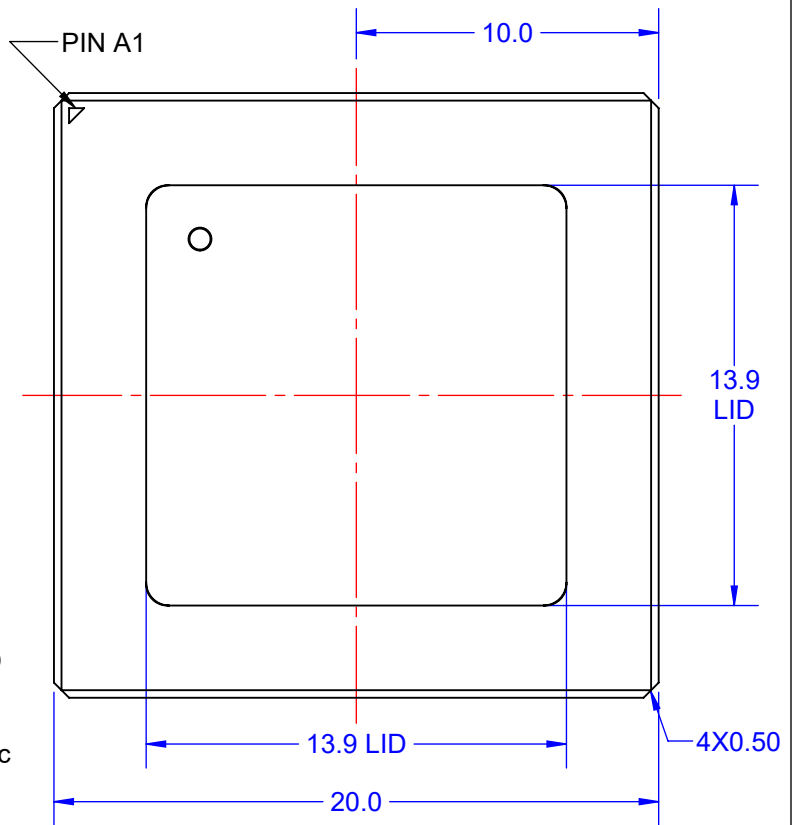
BOTTOM VIEW



SIDE VIEW



TOP VIEW



- Notes: (Unless Otherwise Specified).
 1) DIMENSIONS: MM.
 2) SHOWN WITH COLUMNS.
 3) SHOWN WITH LID COVER ATTACHED.

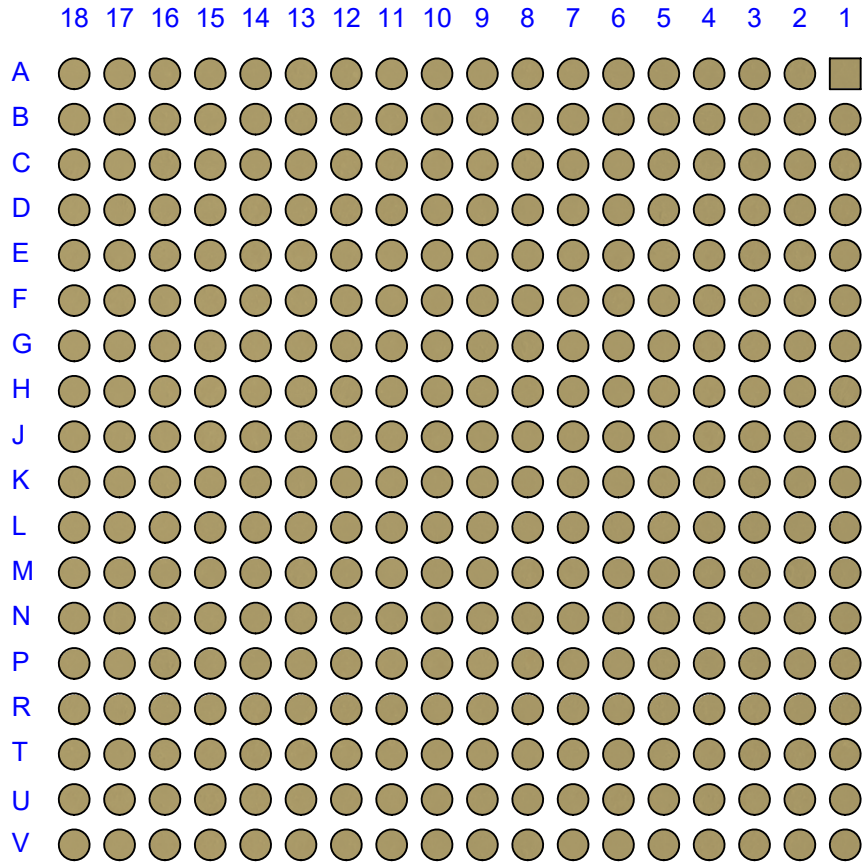
METALLIZATION:
 Ni 1.27 ~ 8.89µm (50 ~ 350 micro-inch)
 Au 0.50µm (38 micro-inch)

PART NUMBER OPTIONS			
PART NUMBER	DIE	SOLDER PIN	LID
CCGA324T1.0-18x18-D	YES	YES	YES

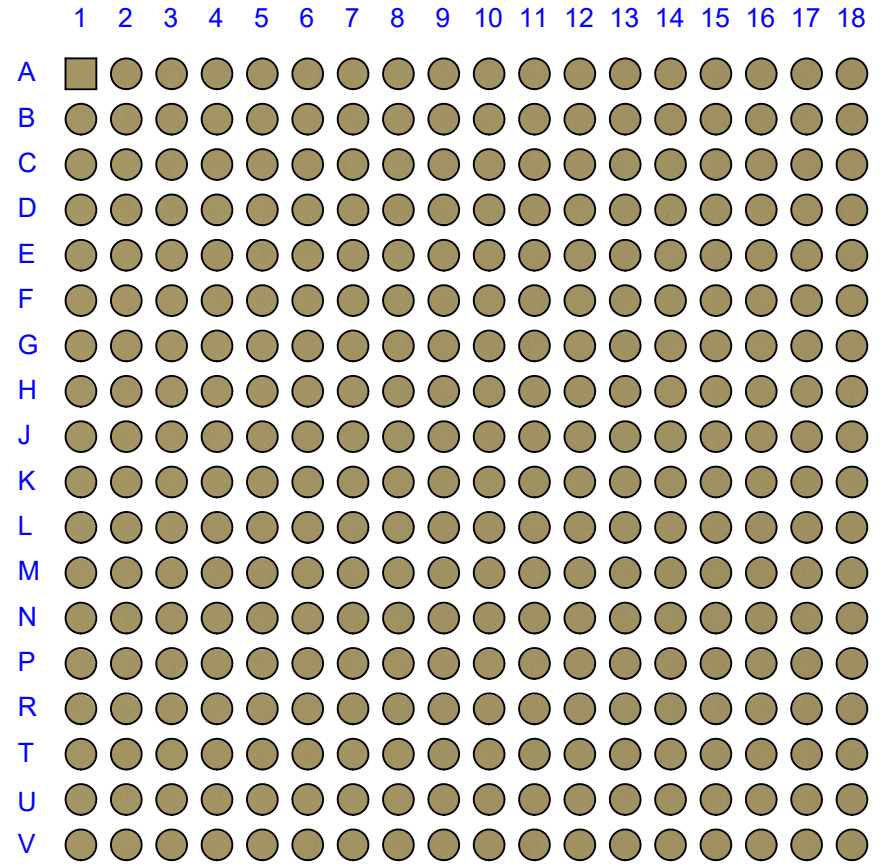
APPROVALS	DATE	TopLine®		
DRAWN T. Au	4/16/2023			
ENG M. Hart	4/16/2023	TITLE CCGA324T1.0-18x18 COLUMN GRID ARRAY		
MFG		SCALE 4:1	SIZE A	DRAWING NO. 160173
QA				REV A
CUST				
REVISED		DO NOT SCALE DRAWING		SHEET 1 OF 3

PAD PATTERN

COLUMN (PAD) VIEW



BOTTOM X-RAY VIEWED FROM TOP



TopLine®

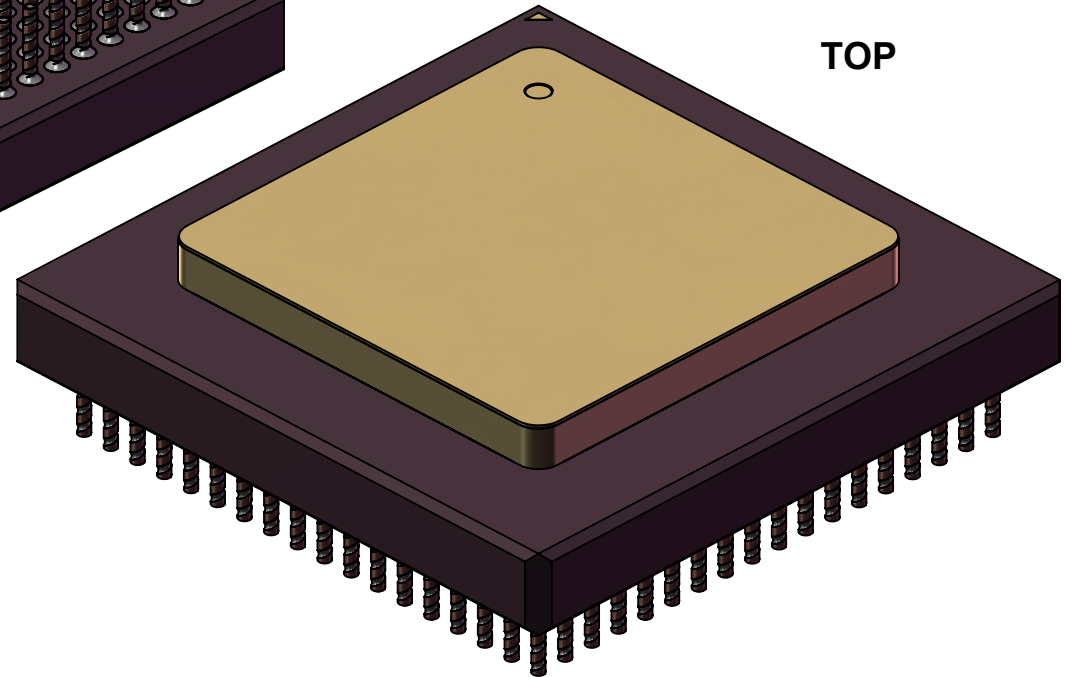
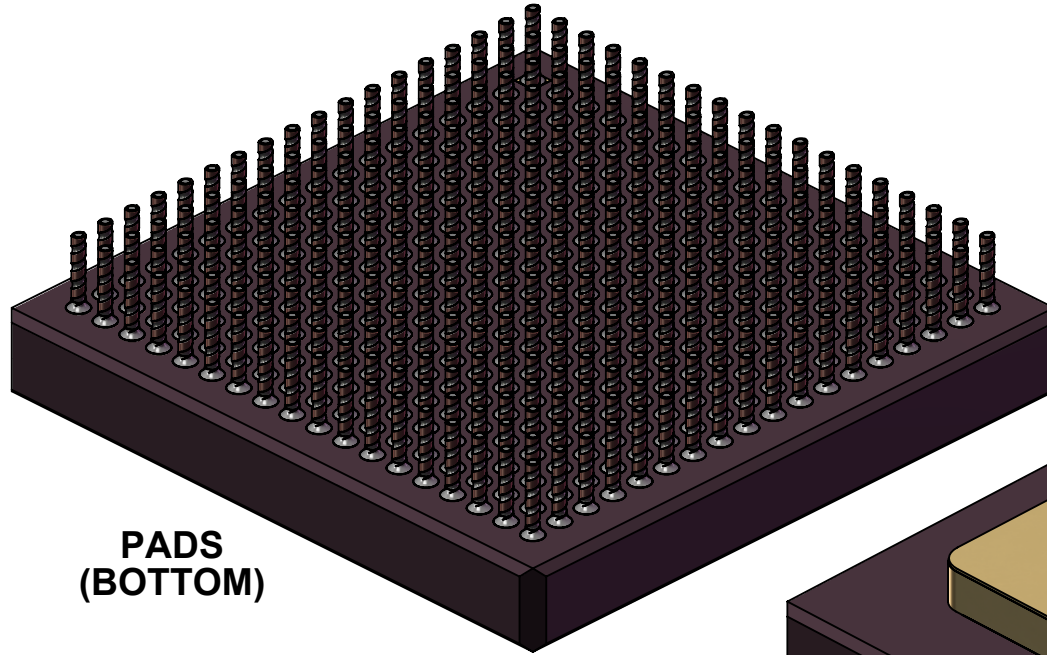
TITLE CCGA324T1.0-18x18
COLUMN GRID ARRAY

SCALE 2.5:1	SIZE A	DRAWING NO. 160173	REV A
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DO NOT SCALE DRAWING

SHEET 2 OF 3

MODEL
CCGA324T1.0-18x18
WITH COLUMNS



TopLine®			
TITLE		CCGA324T1.0-18x18 COLUMN GRID ARRAY	
SCALE	SIZE	DRAWING NO.	REV
5:1	A	160173	A
DO NOT SCALE DRAWING			SHEET 3 OF 3